

# SOT1344-1

plastic fine-pitch land grid array package; 53 lands

8 February 2016

Package information

## 1. Package summary

|                                       |   |
|---------------------------------------|---|
| <b>Terminal position code</b>         | B (bottom)                                |
| <b>Package type descriptive code</b>  | UFLGA53R                                  |
| <b>Package type industry code</b>     | UFLGA53R                                  |
| <b>Package style descriptive code</b> | FLGA (fine-pitch land grid array package) |
| <b>Package style suffix code</b>      | NA (not applicable)                       |
| <b>Package body material type</b>     | P (plastic)                               |
| <b>Mounting method type</b>           | S (surface mount)                         |
| <b>Issue date</b>                     | 28-11-2012                                |

Table 1. Package summary

| Symbol         | Parameter                      | Min   | Typ | Nom   | Max  | Unit |
|----------------|--------------------------------|-------|-----|-------|------|------|
| D              | package length                 | 3.3   | -   | 3.4   | 3.5  | mm   |
| E              | package width                  | 2.85  | -   | 2.95  | 3.05 | mm   |
| A              | seated height                  | [tbd] | -   | [tbd] | 0.52 | mm   |
| e              | nominal pitch                  | -     | -   | 0.4   | -    | mm   |
| n <sub>2</sub> | actual quantity of termination | -     | -   | 53    | -    |      |



2. Package outline

UFLGA53R: plastic fine-pitch land grid array package; 53 lands; SOT1344-1

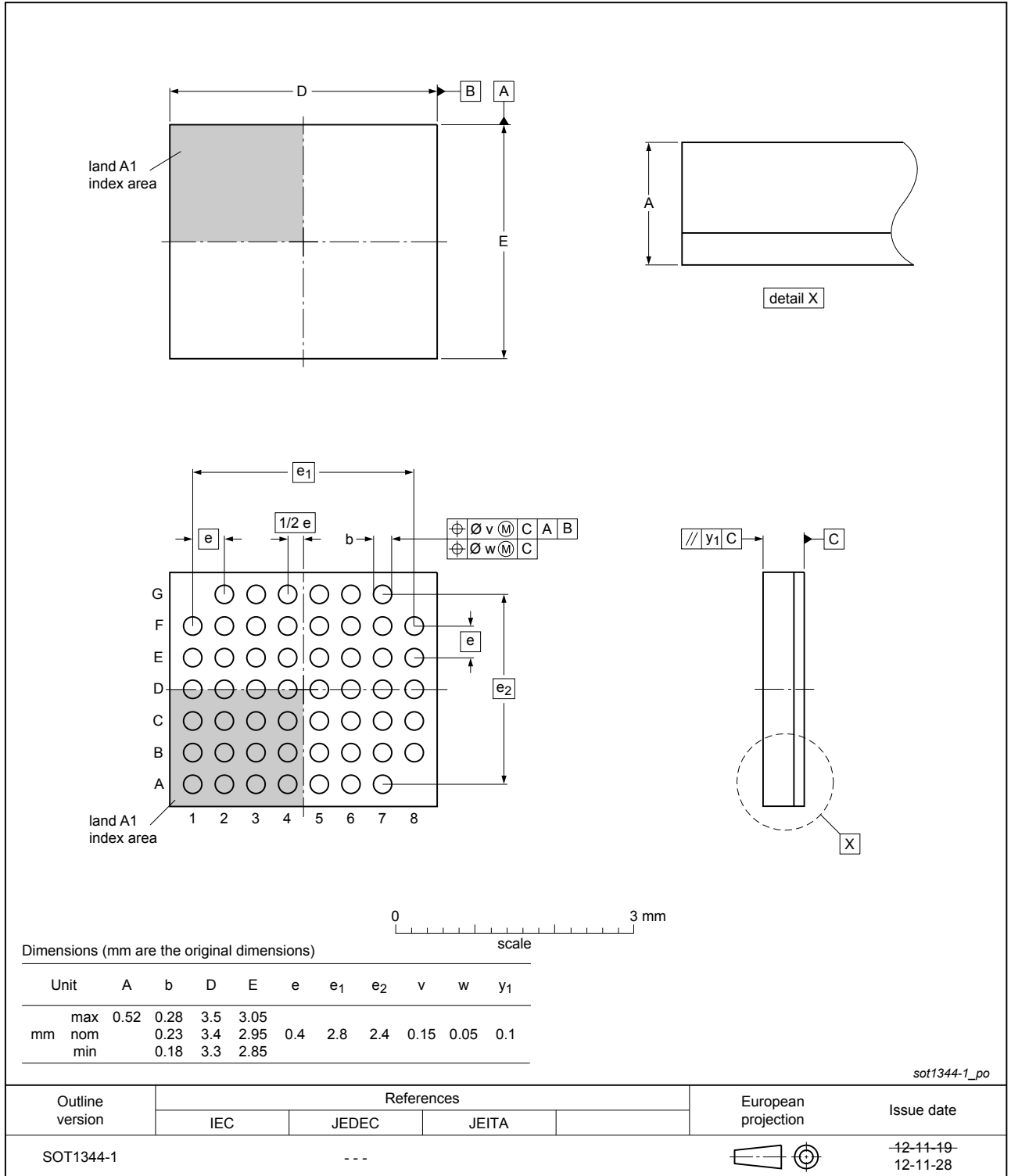


Fig. 1. Package outline UFLGA53R (SOT1344-1)

### 3. Legal information

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